IN THE SPECIFICATION:

Please delete the paragraph beginning on page 6, line 14, and replace with the following new paragraph. Changes from the original are highlighted.

The die attach paddles 400, 410 are made of an electrically conductive material. When placing the semiconductor die (450, as indicated by the dashed box spanning both paddles) onto the paddles 400, 410, the paddles 400, 410 provide separate grounds to the chip. For instance, the chip may comprise an analog and a digital circuit for generating or processing analog and digital signals, respectively. Such a chip may provide on its bottom surface two separate ground contacts, one for establishing an analog ground and the other one for establishing a digital ground. When packaging such chip using the package of FIG. 4, the analog and digital circuits have separate grounds not only on the chip but also in the package. Thus, there are separate grounds within the entire signal path from die to package, and in case of exposed paddles from the paddles to the application board.

Please delete the paragraph beginning on page 6, line 25, and replace with the following new paragraph. Changes from the original are highlighted:

In another configuration, the package of FIG. 4 may encapsulate two separate dies (as indicated by the dashed boxes 460 and 470) in lieu of the single die 450 discussed above, one including analog circuitry and the other including digital circuitry. In this configuration, the die containing the analog circuitry may be placed on paddle 400 while the die containing the digital circuitry is placed on paddle 410. That is, in this arrangement the paddles 400, 410 are used to provide grounds not only to different circuits of the same die but even to different dies. As the paddles 400, 410 are electrically separated, each die may have its own signal path down to the application board.